

Notice of References Cited		Application/Control No.	Applicant(s)/Patent Under Reexamination HAZEYAMA ET AL.	
		Examiner Earl N. Taylor	Art Unit 2818	Page 1 of 1

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*	B	US-5,394,303	02-1995	Yamaji, Yasuhiro	257/777
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)

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